

PT4080L PCI Express® Gen-4 x8 Low-Latency Smart Retimer

1 Benefits and Features

- Compatible with PCIe Gen-4/3/2/1
- 16 GT/s, 8 GT/s, 5 GT/s, and 2.5 GT/s Data Rates with Automatic Link Equalization
- Low-Latency Mode Enables Cache-Coherent Links
- Eight Lanes with Flexible Link Bifurcation Including 1x8, 2x4, 4x2, and Others
- Extends Reach by >28 dB at 16 GT/s Enabling Low-Cost PCB Materials and Connectors
- Receiver and Transmitter Performance Exceeds PCI Express® Base Specification Requirements
- No System Software Required
- BGA Package Footprint Optimized for Board Routing
- Supports SRIS, SRNS, and Common Clock Systems
- Supports Hot Plug and Hot Un-Plug
- Supports Lane Margining at the Receiver for Both Timing and Voltage
- Supports Slave Loopback
- Supports Systems with Lane Reversal and Implements Automatic Polarity Correction
- Low-Power Advanced CMOS Process
- HCSL Reference Clock Output Eliminates Clock Buffers to Drive Downstream PCIe Components
- Advanced In-Band and Out-of-Band Diagnostics for Fleet Management, Large-Scale Server Deployments
- Full-Featured C and Python SDKs for Rapid Integration of Advanced Diagnostics Features
- Device Configuration through SMBus or EEPROM
- IEEE 1149.6 AC-JTAG Boundary Scan
- Full Portfolio of Pin- and Register-Compatible Retimers Enables Easy Performance Scaling Up to PCI Express® Gen-5

2 Applications

- Server and High-Performance PC Motherboards
- PCIe Riser and Add-in Cards
- Server-to-Server Cabled Interfaces
- NVMe JBODs, GPU/Deep-Learning Accelerators

Product Family Information – x16, x8

| Part # | PCIe Gen | Lanes | Package | Body Size (Nom) |
|---------|----------|-------|--------------|------------------|
| PT5161L | Gen-5 | 16 | FC-CSP (354) | 8.9 mm x 22.8 mm |
| PT4161L | Gen-4 | 16 | FC-CSP (354) | 8.9 mm x 22.8 mm |
| PT5081L | Gen-5 | 8 | FC-CSP (332) | 8.5 mm x 13.4 mm |
| PT4080L | Gen-4 | 8 | FC-CSP (332) | 8.5 mm x 13.4 mm |

3 Description

The PT4080L is an 8-Lane PCI Express® (PCIe) Gen-4 protocol-aware low-latency Retimer designed to integrate seamlessly between a Root Complex and End Point(s) extending the reach by >28 dB at 16 GT/s. Compliant to all PCIe 4.0 rates and Retimer functional requirements, the PT4080L enables more system topologies and lower total solution cost while minimizing implementation overhead and Bill of Materials (BoM).

The innovative protocol-non-disruptive low-latency architecture of PT4080L significantly reduces latency through the Retimer while being transparent to system software and participating in Link Equalization with the Root Complex and End Point(s) to optimize Link performance. The PT4080L can autonomously adapt its latency to maximize performance during normal operational Link state (L0) while maintaining protocol interoperation.

To support a wide variety of End Points and port configurations, the PT4080L can bifurcate to one x8 Link, two x4 Links, four x2 Links, and more. Each Link operates independently, and per-Link diagnostics information such as Link state history and electrical margin are accessible through in-band (Receiver margining) and out-of-band (SMBus) methods.

The PT4080L uses a standard PCIe 100-MHz HCSL input clock and provides a 100-MHz HCSL output clock to drive other Retimer devices or PCIe components in the system.

The pinout is based on the Intel Retimer Supplemental Specification and uses an 8.5-mm x 13.4-mm Flip-Chip CSP package. The pinout allows for separate single-layer routing for all high-speed transmit and receive signals. Compact design and minimal supporting circuitry greatly reduces overall solution size, making the PT4080L ideal for space-restricted applications like system boards and riser cards.

Typical Application Block Diagram

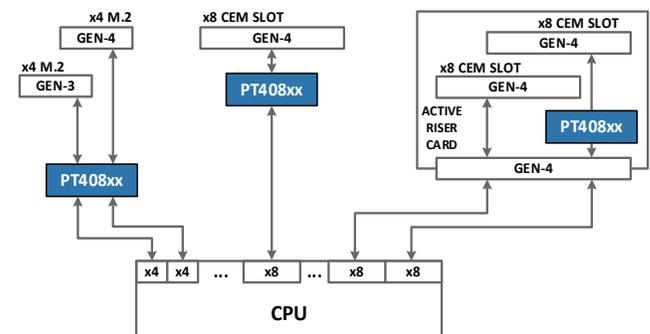


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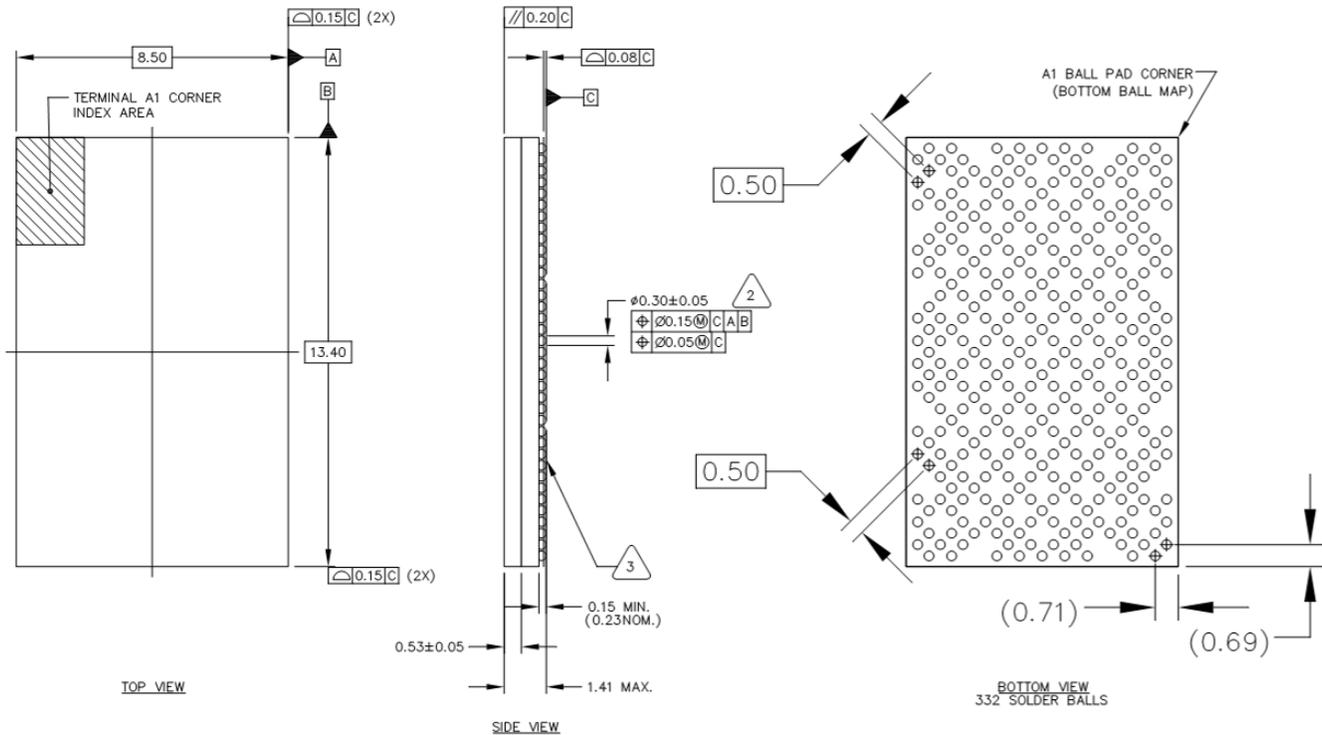
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4 Revision History

| Revision | Date | Changes |
|----------|---------------|--|
| - | December 2020 | <ul style="list-style-type: none">Release of Production Data Datasheet (abridged, product brief form). |

5 Package, Mechanical, and Orderable Information

5.1 Package Outline Drawing



3. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS
2. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
1. REFERENCE SPECIFICATIONS:
 A. AWW SPEC #001-2234: PACKING OPERATION PROCEDURE
 B. AWW SPEC #001-2062: MARKING
- NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS

DECIMAL ANGULAR
 X.X ±0.1 ±1°
 X.XX ±0.05
 X.XXX ±0.030

INTERPRET DIM AND TOL PER ASME Y14.5 - 2009

Figure 5-1: Package Outline Drawing

Table 5-1: Package Dimensions

| Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------|--------------------------|------|------|------|------|
| Package width | | 8.45 | 8.50 | 8.55 | mm |
| Package length | | 13.3 | 13.4 | 13.5 | mm |
| Package thickness | Prior to BGA compression | 1.21 | 1.31 | 1.41 | mm |

5.2 Package Land Pattern

Figure 5-2 shows the top view of the platform-side land pattern for the PT4080L.

NOTE: Refer to “Astera_Labs_PT4080L_supplemental_info.xlsx” for detailed land pad coordinates, sizes, and rotation.

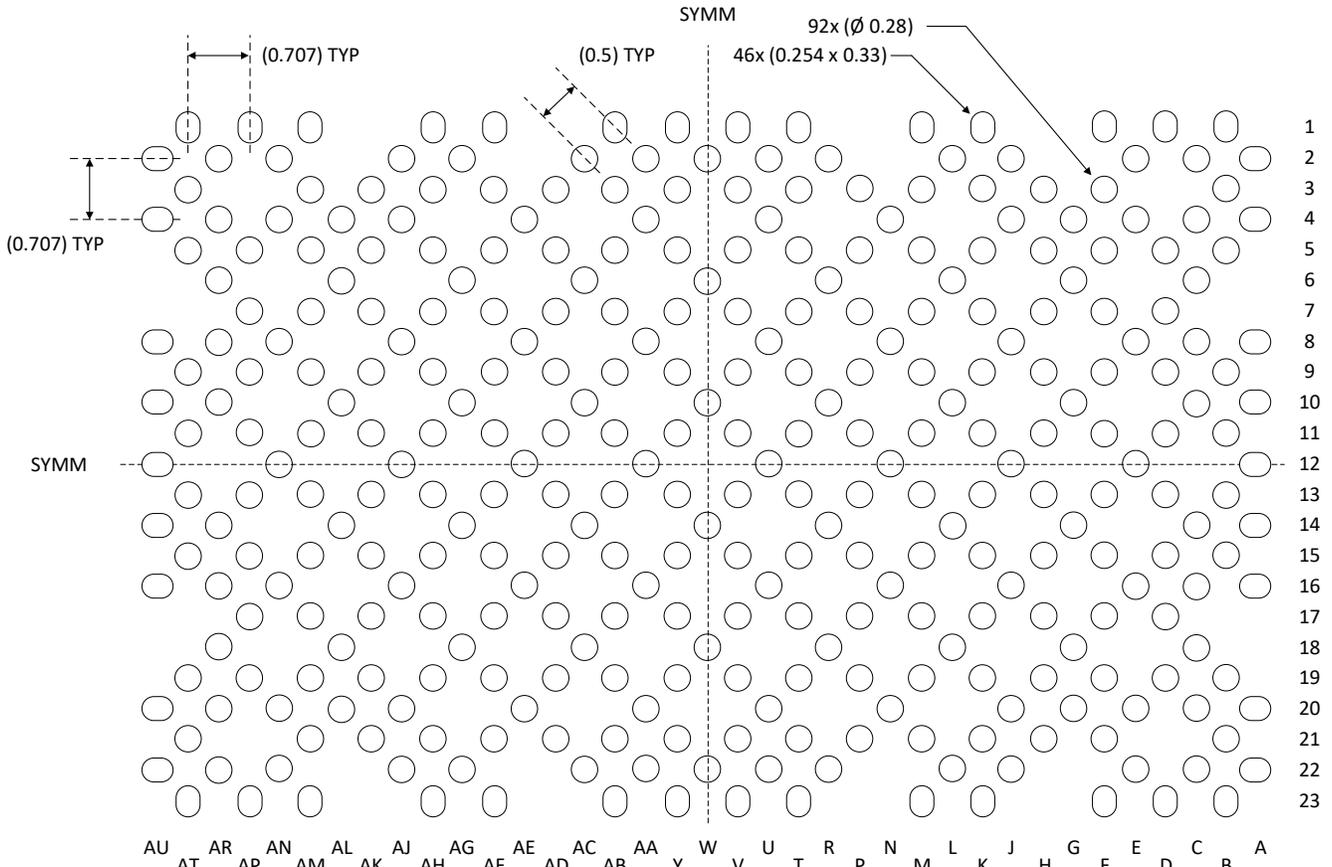


Figure 5-2: Package Land Pattern (Top View)

5.3 Package Solder Mask Stencil

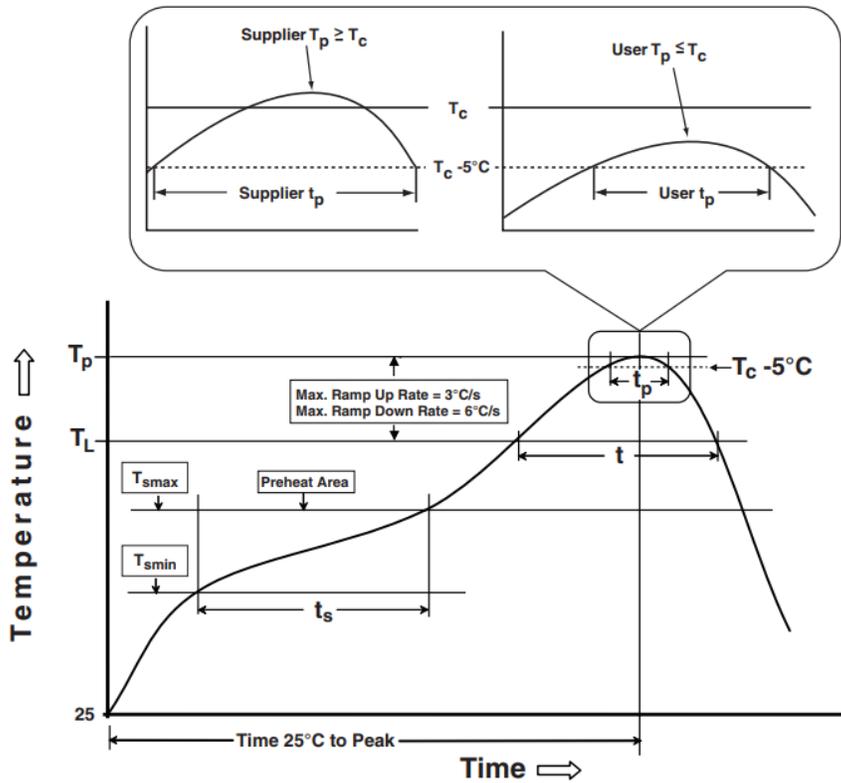
Asteralabs recommends keeping the solder paste aperture the same size as the land pads, shown in Figure 5-2 and using metal-defined (MD) pads rather than solder-mask-defined (SMD) pads.

5.4 Reflow Profile

Asteralabs recommends an assembly reflow profile consistent with lead-free assembly as outlined in the IPC/JEDEC J-STD-020E standard. Table 5-2 provides a rough guideline, however specific parameters such as peak temperature, peak temperature duration may need to be adjusted based on other system components.

Table 5-2: Guideline Lead-Free Assembly Reflow Parameters

| Profile Feature | Lead-Free Assembly | Units |
|---|--------------------|-------------|
| Ramp-up rate | 1.5 to 3 | °C / second |
| Preheat temperature | 25 to 183 | °C |
| Preheat time | 150 | seconds |
| Time maintained above T _L | 70 to 80 | seconds |
| T _L | 221 | °C |
| Peak temperature | 250 to 255 | °C |
| Time within 5 °C of peak temperature | 20 to 30 | seconds |
| Ramp-down rate (T _{peak} to T _L) | 3 | °C / second |
| Time from 25 °C to peak temperature | 4 | minutes |



IPC-020e-5-1

Figure 5-3: Reflow Profile from IPC/JEDEC J-STD-020E (Not to Scale)

5.5 Orderable Information

Table 11-3: Device Orderable Information

| Base Part Number | Orderable Part Number | Package | Maximum PCIe Gen ⁽¹⁾ | PCIe Lanes | Integrated AC Coupling Capacitors | Operating Junction Temperature | Pack Quantity | Top Marking ⁽²⁾ | Eco Status ⁽³⁾ | MSL Peak Temp ⁽⁴⁾ | Product Revision ⁽⁵⁾ |
|------------------|-----------------------|----------------|---------------------------------|------------|-----------------------------------|--------------------------------|---------------|---|---------------------------|------------------------------|---------------------------------|
| PT4080L | PT4080LRS | 332-pin FC-CSP | Gen-4 | x8 | No | -10 °C to 110 °C | 180 |  | EU-RoHS, Halogen-Free | Level-3-260C-168 HR | Production |
| | PT4080LRL | 332-pin FC-CSP | Gen-4 | x8 | No | -10 °C to 110 °C | 1800 |  | EU-RoHS, Halogen-Free | Level-3-260C-168 HR | Production |

(1) Astera Labs products support 100% backwards compatibility to earlier PCIe generations, unless otherwise noted.

(2) YYWW is a date code, ##### is a lot trace code. There may be additional marking, which relates to the logo or the lot trace code.

(3) Astera Labs defines “EU-RoHS” to mean products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, “RoHS” products are suitable for use in specified lead-free processes. Astera Labs defines “Halogen-Free” to mean semiconductor products that are compliant with JS709B low-halogen requirements of ≤1000 ppm threshold.

(4) Moisture Sensitivity Level rating according to the JEDEC industry standard classifications and peak solder temperature.

(5) Astera Labs defines “Pre-production” as the final product revision which is undergoing full production qualification; and “Production” as the final product revision which has been qualified per applicable JEDEC standards.